

Patent Abstracts of Japan

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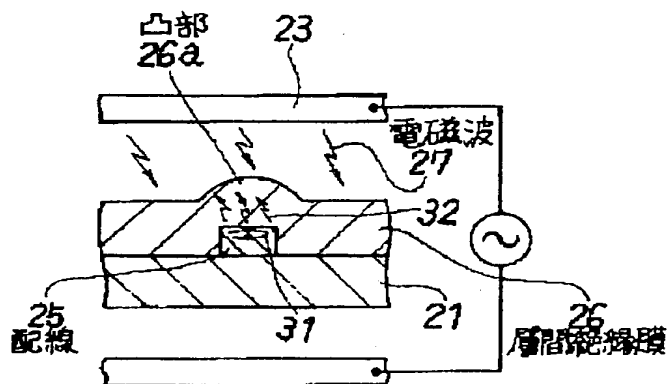
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TITLE : METHOD FOR FLATTENING
INTERLAYER INSULATING FILM



ABSTRACT : PURPOSE: To provide a layer insulating film with uniform and excellent flatness so that manufacturing accuracy in wiring pattern can be improved.

CONSTITUTION: A wiring 25 is patterned on a wafer 21, and the wiring 25 is coated with a layer insulating film 26. Electromagnetic waves 27 are directed to the wafer 21, and Joule's heat 32 is generated by an eddy current 31 in the wiring 25. Then, only a projected part 26a on the wiring 25 in the layer insulating film 26 becomes fluid by heat, and only the projected part 26a flows into a recessed part through gravitation so that the layer insulating film 26 is flattened.

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